As the pioneer in P.B.S.® brazed bonding for CMP pad conditioning disks, Abrasive Technology has set the industry standards for performance, consistency and efficiency.

**FEATURES**

- Operate on all major CMP equipment platforms in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu) processes.

- Specialized manufacturing technology to control critical abrasive specifications (diamond size, shape, bond height, diamond plane), which delivers high performance.

- Ideal for both in-situ and ex-situ CMP processes to meet critical CMP process requirements.

- Available in magnetic and non-magnetic grades of stainless steel in variety of front surface configurations and sizes.

**THE P.B.S.® ADVANTAGE**

- Individually and permanently brazes diamonds in place, increasing crystal retention.

- Greater control over crystal concentration, creating a more consistent pad surface.

- Chemical bond is more durable than electroplated and protects the crystals, extending the life of each disk.
Abrasive Technology’s P.B.S.® brazed disks for CMP pad conditioning are precisely manufactured for the highest productivity in semiconductor wafer processing. Our disks are customized to operate on Oxide, Tungsten and Copper processes.

**Performance:**
Third party testing confirmed consistent, high-performance results on AT disks when compared to the leading competitor.

**Value:**
Users achieve lower cost of ownership with AT disk:
- Improve price
- Higher quality
- Consistent performance

**Customer Data: Tungsten Process**

**Polishing Tool:**
EPO112-T/300mm AiGIIS Head

**Polish Pad:**
IC1000K/SubaIV

**Slurry:**
Cabot

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**Diameter Scan (81 pt)**

**Competitor A vs. AT Disk 1**

<table>
<thead>
<tr>
<th>Competitor A</th>
<th>AT Disk 1</th>
</tr>
</thead>
<tbody>
<tr>
<td>Removal rate: 2699A/min</td>
<td>Removal rate: 2940 A/min</td>
</tr>
<tr>
<td>WIWNU: 1.33% 5mmEE</td>
<td>WIWNU: 1.31% 5mmEE</td>
</tr>
</tbody>
</table>

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**Diameter Location (mm)**

**Tungsten Removed**

**MRR (A/min)**

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